L	Hits	Search Text	DB	Time stamp
Number				
4	495	(polish\$3 adj pad) same window	USPAT;	2004/08/30
			US-PGPUB;	17:52
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	5	(planar\$3 adj pad) same window	USPAT;	2004/08/30
			US-PGPUB;	17:53
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	48	(polish\$3 adj pad) same window same	USPAT;	2004/08/30
		(notch or groove)	US-PGPUB;	17:53
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
16	0	conductive adj planarizing adj pad	USPAT;	2004/08/30
			US-PGPUB;	18:22
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	27	conductive adj polishing adj pad	USPAT;	2004/08/30
			US-PGPUB;	18:28
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	